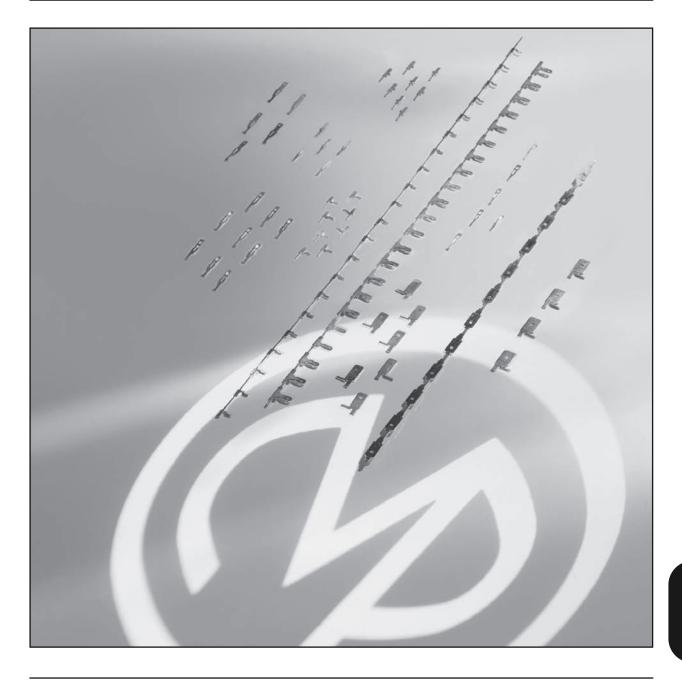
TERMINALS

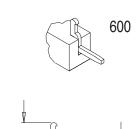


- All terminals & wire are now converted to lead free
- TBS 900 series to suit A and S ranges
- TBS 600 series to suit M range
- Solderability test to BS 2011 1981
- Round, square and serrated wire available
- Retention tests performed to assure connnection integrity





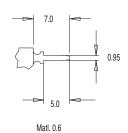
TBS 600 Range Terminals (P.C.B. Type)



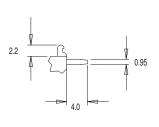
5.0

Matl. 0.6



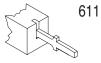


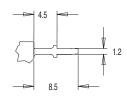




Matl. 0.5

621*



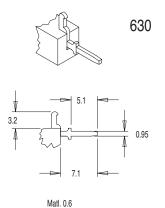


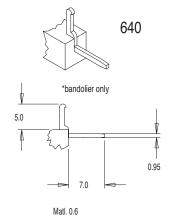
Matl. 0.6

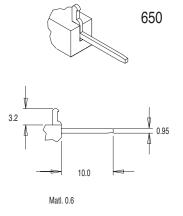




Matl. 0.5



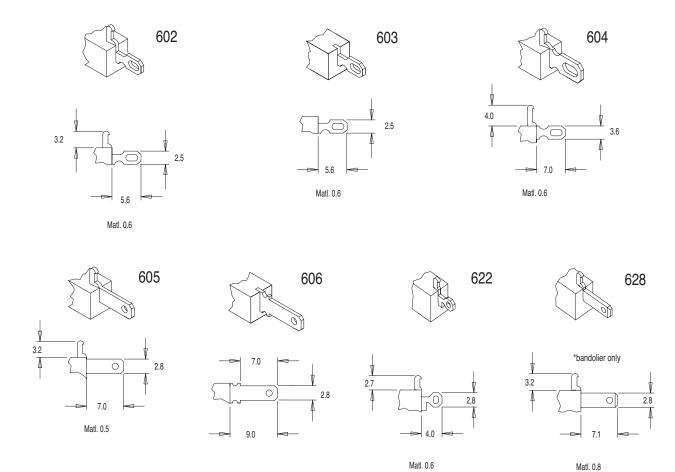


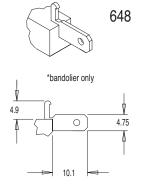


Standard materials: CZ108 (CuZn37) half hard brass with 100% matt tin finish. Solderability test to BS2011: 1981. Dimensions in millimetres. All terminals are lead-free. *Contact sales office for availability.

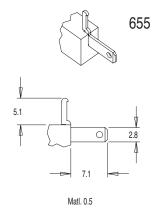


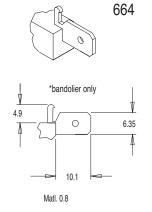
TBS 600 Range Terminals (Solder/Fast-on Type)





Matl. 0.8





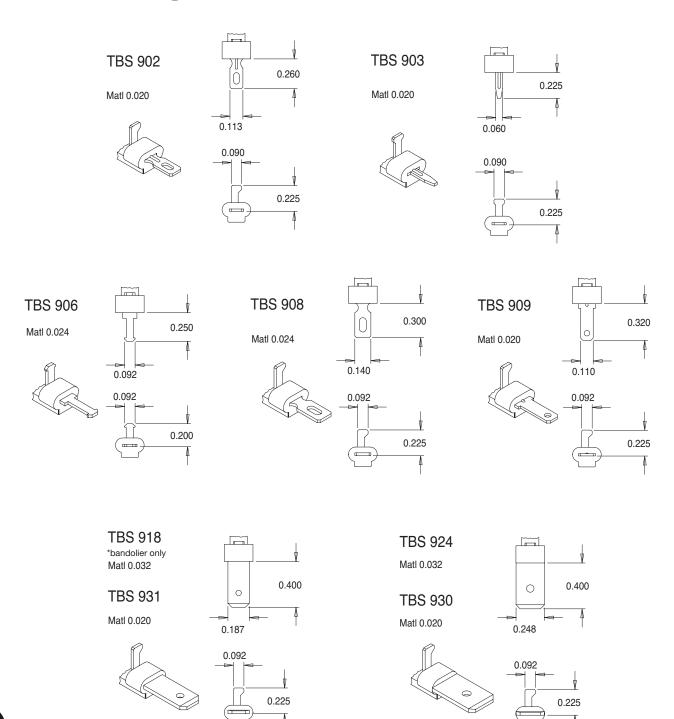
Standard materials: CZ108 (CuZn37) half hard brass with 100% matt tin finish Solderability test to BS2011: 1981 Dimensions in millimetres All terminals are lead-free

Terminals

For 'S' or 'A' Range Bobbins



TBS 900 Range (Standard Terminal Pocket)



Standard materials: CZ108 (CuZn37) half hard brass with 100% matt tin finish Solderability test to BS2011: 1981 Dimensions in inches All terminals are lead-free



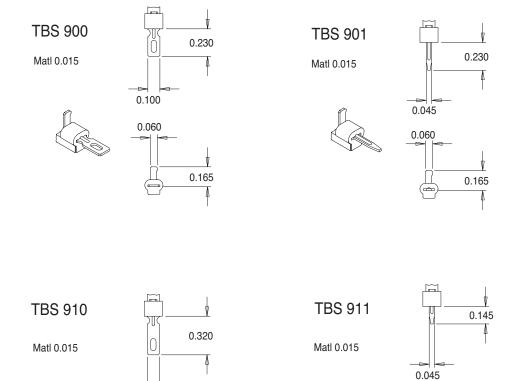
Terminals

For 'S' or 'A' Range Bobbins



TBS 900 Range

Small Terminal Pocket for 18 (US EI-560), 145 (US EI-625) & 74 (US EI-68) Bobbin Sizes



Standard materials: CZ108 (CuZn37) half hard brass with 100% matt tin finish Solderability test to BS2011: 1981 Dimensions in inches All terminals are lead-free

0.233

0.100

0.060

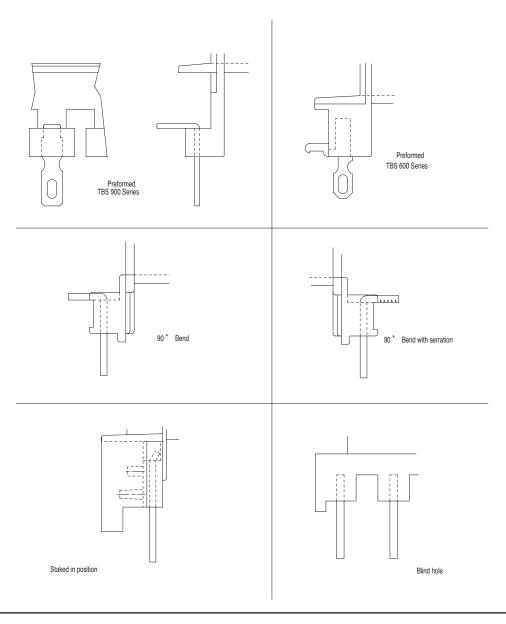


0.060

0.165

Pin Insertion Methods





Glossary of Terms - The following is a selected list of industry related terms associated with solderability.

Activator A compound added to flux to increase flux efficacy.

Cold Joint A commonly used term that refers to a poor quality solder joint.

DewettingRetreat of solder from all or part of joint surfaces, which were initially wetted, leaving an insufficient layer of solder.

The method of soldering adopted by Miles-Platts in which the material to be soldered is fluxed, then dipped into a bath of

molten solder.

Dross Oxidised solder that forms as a residue in solder baths.

Efficacy Term used to describe the level of fluxing activity exhibited by a particular flux.

Flux Material used to improve the flow properties of molten solder and the wetting of metallic substrates.

Liquidus The temperature at which an alloy becomes fully liquid.

Solderability The term used to measure the ease with which a material may be soldered with a particular combination of solder and flux.

Tinning

A pre-coating of a metallic surface with molten solder to protect from oxidation and preserve solderability.

Wetting

Spreading of a coating of molten solder on a metallic substrate and production of an intermetallic compound.



